

Application No.: 10/055,568

Docket No.: JCLA8533

**REMARKS**

This is a full and timely response to the outstanding final Office Action mailed June 8, 2004. Reconsideration and allowance of the application and presently added claims are respectfully requested.

**1. Present Status of the Application**

Upon entry of the amendments in this response, claims 143-167 are added in the present application. More specifically, claims 1-142 are directly canceled. These additions are specifically described above. It is believed that the foregoing additions add no new matter to the present application.

**2. Response To Objections/Rejections**

Applicants respectfully traverse the rejections for at least the reasons set forth below.

**Response To Claim Rejections Under 35 U.S.C. Section 102**

As originally recited, independent claim 143 recites below:

143. A chip package structure comprising:

***a substrate comprising silicon;***

**only one die mounted to said substrate**, said die having an active surface, an internal circuitry and a plurality of active devices, said active surface including multiple pads electrically connected to said active devices through said internal circuitry, said substrate having a surface not covered by said die; and

**at least one patterned line extending over said active surface of said die and over said surface of said substrate**, said patterned line electrically connected to one of said pads, said patterned line constructed from at least a patterned circuit layer.

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*(emphasis added)*

Ma discloses that an encapsulating material 112 such as plastics, resins encapsulates only die 102. [See Fig. 1b and lines 4-9, col. 3] Ma fails to disclose the encapsulating material 112 may comprise silicon. However, the present invention discloses that the substrate to which only one die is mounted comprises silicon, which is claimed in claim 143 as bold. Moreover, the above subject matter is allowed in the final Office Action.

**Response To Claim Rejections Under 35 U.S.C. Section 103**

One of the features in accordance with the present invention is that only one die is mounted to a substrate comprising silicon. However, both of the citations by Ma and Ishide fail to teach, suggest or hint the above feature. Therefore, even though the citations by Ma and Ishida are combined, the subject matters claimed in claim 143 can not be attained. Moreover, the above subject matter is allowed in the final Office Action.

For at least the foregoing reasons, Applicants respectfully submit that the independent claim 143 patently define over the prior art references, and should be allowed. For at least the same reasons, dependent claims 144-167 patently define over the prior art as well.

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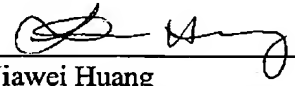
**CONCLUSION**

For at least the foregoing reasons, it is believed that the pending claims 143-167 are in proper condition for allowance. If the Examiner believes that a telephone conference would expedite the examination of the above-identified patent application, the Examiner is invited to call the undersigned.

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Respectfully submitted,  
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